

# Ruey-Beei Wu

## List of Publications by Year in descending order

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199  
papers

3,371  
citations

126708

33  
h-index

174990

52  
g-index

199  
all docs

199  
docs citations

199  
times ranked

1816  
citing authors

#	ARTICLE	IF	CITATIONS
1	Optimization and Evaluation of Multidetector Deep Neural Network for High-Accuracy Wi-Fi Fingerprint Positioning. IEEE Internet of Things Journal, 2022, 9, 15204-15214.	5.5	2
2	Positioning for Search and Rescue in GPS-Denied Area by Distributed WiFi RSS-Based DoA Modules. IEEE Access, 2022, 10, 76105-76113.	2.6	2
3	Design for Acoustic Wave Multiplexers With Single Inductor Matching Network Using Frequency Response Fitting Method. IEEE Open Journal of Ultrasonics, Ferroelectrics, and Frequency Control, 2022, 2, 140-151.	0.9	4
4	Modeling and Mitigating Fiber Weave Effect Using Layer Equivalent Model and Monte Carlo Method. , 2022, , .		0
5	Symmetric-Cell EBG Theory and Its Applications to Vias Daisy Chain for Residual Stub Detection. , 2022, , .		0
6	Systematic Design for Mitigation of RF Desense by Interleaved Power Line in Two-Layer PCB. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 859-864.	1.4	1
7	Physical Tampering Detection Using Single COTS Wi-Fi Endpoint. Sensors, 2021, 21, 5665.	2.1	7
8	Synthesis of Chebyshev/Elliptic Filters Using Minimum Acoustic Wave Resonators. IEEE Access, 2019, 7, 103456-103462.	2.6	14
9	Nonperiodic Flipped EBG for Dual-Band SSN Mitigation in Two-Layer PCB. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1690-1697.	1.4	5
10	A Phenomenological Approach Based on Two Unified Loss Parameters for Transient Analysis of Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2219-2226.	1.4	1
11	A Novel Desensitization Using Resonance Suppressors in Metallic Shielding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1680-1689.	1.4	2
12	SI Analysis of Electro-Optic Interconnects for Next Generation SerDes in WLP-SiP. , 2019, , .		0
13	Reduction of Common-Mode Noise in Bent Differential Interconnects for PAM4 Signaling. , 2019, , .		0
14	An Interactive Web-based Learning Module for Metallic Rectangular Waveguides. , 2019, , .		0
15	Interleaved Power Transmission Line for Mitigation of Digital to RF De-sense. , 2019, , .		2
16	A Novel Dual-Sided Fly-By Topology for 1â€“8 DDR With Optimized Signal Integrity by EBG Design. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1823-1829.	1.4	7
17	Miniaturized Tunable Filters with T-Coil Design. , 2018, , .		0
18	Non-Periodic Flipped-SIR EBG for Dual-Band SSN Mitigation in 2-Layer PCB. , 2018, , .		1

#	ARTICLE	IF	CITATIONS
19	Suppression of noise from digital-to-analog coupling in shielding cavity. , 2018, , .		1
20	Novel RDL Design of Wafer-Level Packaging for Signal/Power Integrity in LPDDR4 Application. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 1431-1439.	1.4	10
21	Three-way cascade power divider and combiner for satellite communications. , 2017, , .		8
22	The competitions of electromagnetic for undergraduate students in Taiwan: Taiwan creative electromagnetic implementation competition T-CEIC. , 2017, , .		0
23	A Novel Two-Cap Filter for Routing Noise Suppression Using Extended EBG Analysis. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 1852-1858.	1.4	3
24	A 77-GHz 2T6R Transceiver With Injection-Lock Frequency Sextupler Using 65-nm CMOS for Automotive Radar System Application. IEEE Transactions on Microwave Theory and Techniques, 2016, 64, 3031-3048.	2.9	55
25	Varactor-Tuned Compact Dual-Mode Tunable Filter With Constant Passband Characteristics. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1399-1407.	1.4	40
26	Design of compact microwave filter using vertically interdigitated resonators. , 2015, , .		0
27	Design of 2-in-1 bandpass filter using common dual mode resonators. , 2015, , .		0
28	A miniaturized bandpass filter using double folded dual-mode cavity resonators in LTCC. , 2015, , .		0
29	Design of stackup and shorting vias and for reducing edge radiation in multilayer PCB. , 2015, , .		1
30	Ringling Noise Suppression for Differential Signaling in Unshielded Flexible Flat Cable. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2015, 5, 1152-1159.	1.4	3
31	Artificial neural network modeling for Extrinsic capacitance of FinFET. , 2014, , .		0
32	Efficient multi-node optimal placement for decoupling capacitors on PCB. , 2014, , .		6
33	Modeling and Fast Eye Diagram Estimation of Ringing Effects on Branch Line Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 641-647.	1.4	1
34	Fast Prediction and Optimal Design for Eye-Height Performance of Mismatched Transmission Lines. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 896-904.	1.4	6
35	Triband Filter Design Using Laminated Waveguide Cavity in LTCC. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 957-966.	1.4	26
36	Design of Single-Branch Laminated Waveguide Diplexers Using Modal Orthogonality. IEEE Transactions on Microwave Theory and Techniques, 2013, 61, 4079-4089.	2.9	28

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37	Development of millimeter-wave passive components and system-in-packages by LTCC technology. , 2013, , .		0
38	Characterization of TSVs by cascaded daisy chains. , 2013, , .		0
39	Design of a 180-degree hybrid with Chebyshev filtering response using coupled resonators. , 2013, , .		14
40	Design of Miniaturized Filtering Power Dividers for System-in-a-Package. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1663-1672.	1.4	101
41	Millimeter-wave non-contact flip-chip transitions with Chebyshev filtering response using coupled microstrip resonators. , 2013, , .		0
42	Modified pseudo eye metric for mismatched transmission lines. , 2013, , .		0
43	Development of wideband electrically identical fan-out structure for 60 GHz frontend phased array system in package module. , 2012, , .		1
44	An integrated filtering antenna array with 180 degree hybrid for SiP front end module. , 2012, , .		4
45	Enhanced eye-height estimation of mismatched lossy transmission lines. , 2012, , .		2
46	A compact filtering rat-race coupler using dual-mode stub-loaded resonators. , 2012, , .		19
47	60-GHz Four-Element Phased-Array Transmit/Receive System-in-Package Using Phase Compensation Techniques in 65-nm Flip-Chip CMOS Process. IEEE Transactions on Microwave Theory and Techniques, 2012, 60, 743-756.	2.9	177
48	Design considerations for radio frequency 3DICs. , 2012, , .		0
49	A linear 4-element model of VRM &#x2014;Characteristics, practical uses and limitations. , 2012, , .		7
50	Antenna Design of 60-GHz Micro-Radar System-In-Package for Noncontact Vital Sign Detection. IEEE Antennas and Wireless Propagation Letters, 2012, 11, 1702-1705.	2.4	42
51	LTCC embedded laminated waveguide filters and couplers for microwave SiP applications. , 2011, , .		0
52	Design of Microstrip-to-Microstrip Via Transition in Multilayered LTCC for Frequencies up to 67 GHz. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 595-601.	1.4	50
53	Passive Equalizer Design for Through Silicon Vias With Perfect Compensation. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1815-1822.	1.4	19
54	Design of Multimode Net-Type Resonators and Their Applications to Filters and Multiplexers. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 848-856.	2.9	65

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55	Design of Compact Quadruplexer Based on the Tri-Mode Net-Type Resonators. IEEE Microwave and Wireless Components Letters, 2011, 21, 534-536.	2.0	62
56	Modeling and Optimal Design of Shorting Vias to Suppress Radiated Emission in High-Speed Alternating PCB Planes. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 566-573.	1.4	16
57	Direct Eye Diagram Optimization for Arbitrary Transmission Lines Using FIR Filter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 1250-1258.	1.4	18
58	Passive FIR filter design using reflections from stubs for high speed links. , 2011, , .		0
59	A Laminated Waveguide Magic-T With Bandpass Filter Response in Multilayer LTCC. IEEE Transactions on Microwave Theory and Techniques, 2011, 59, 584-592.	2.9	51
60	Design of quadruple-passband microwave filters using frequency transformation. , 2011, , .		0
61	Optimal decoupling capacitors design for suppressing edge radiation of power/ground planes. , 2011, , .		3
62	SI-aware layout and equalizer design to enhance performance of high-speed links in blade servers. , 2011, , .		5
63	A New Isolation Structure of Pogo Pins for Crosstalk Reduction in a Test Socket. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2011, 1, 586-594.	1.4	15
64	Signal/Power Integrity Modeling of High-Speed Memory Modules Using Chip-Package-Board Coanalysis. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 381-391.	1.4	28
65	Optimization of FIR filter to improve eye diagram for general transmission line systems. , 2010, , .		2
66	Enhanced Microstrip Guard Trace for Ringing Noise Suppression Using a Dielectric Superstrate. IEEE Transactions on Advanced Packaging, 2010, 33, 961-968.	1.7	26
67	Compromise Impedance Match Design for Pogo Pins With Different Single-Ended and Differential Signal-Ground Patterns. IEEE Transactions on Advanced Packaging, 2010, 33, 953-960.	1.7	12
68	A Wideband Common-Mode Suppression Filter for Bend Discontinuities in Differential Signaling Using Tightly Coupled Microstrips. IEEE Transactions on Advanced Packaging, 2010, 33, 969-978.	1.7	67
69	Tri-band filter design using substrate integrated waveguide resonators in LTCC. , 2010, , .		9
70	RC passive equalizer for through silicon via. , 2010, , .		3
71	A new isolation structure for crosstalk reduction of pogo pins in a test socket. , 2009, , .		4
72	Dual-Band Vertically Stacked Laminated Waveguide Filter Design in LTCC Technology. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1554-1562.	2.9	76

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73	Miniaturized Bandpass Filters With Double-Folded Substrate Integrated Waveguide Resonators in LTCC. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1774-1782.	2.9	99
74	Design of Tri-Band Filters With Improved Band Allocation. IEEE Transactions on Microwave Theory and Techniques, 2009, 57, 1790-1797.	2.9	67
75	A system-on-package integration of X-band FMCW sensor RF frontend module. , 2009, , .		1
76	Design of shorting vias in alternative PCB planes for suppressing ground-bounce induced electromagnetic emission. , 2009, , .		1
77	Design of lumped rat-race coupler in multilayer LTCC. , 2009, , .		17
78	A wide-band microstrip-to-microstrip multi-layered via transition using LTCC technology. , 2009, , .		0
79	A laminated waveguide magic-T in multilayer LTCC. , 2009, , .		6
80	Compromised impedance match design for signal integrity of pogo pins structures with different signal-ground patterns. , 2009, , .		8
81	Miniaturized rat-race coupler with bandpass response and good stopband rejection. , 2009, , .		34
82	Fast Methodology for Determining Eye Diagram Characteristics of Lossy Transmission Lines. IEEE Transactions on Advanced Packaging, 2009, 32, 175-183.	1.7	39
83	Reduction in Reflections and Ground Bounce for Signal Line Over Slotted Power Plane Using Differential Coupled Microstrip Lines. IEEE Transactions on Advanced Packaging, 2009, 32, 581-588.	1.7	21
84	A Dual Wideband Filter Design Using Frequency Mapping and Stepped-Impedance Resonators. IEEE Transactions on Microwave Theory and Techniques, 2008, 56, 2921-2929.	2.9	60
85	Highly Directed Radiation Pattern From a THz Photonic Transmitter With a Two-Dimensional Rampart Slot Array Antenna. IEEE Photonics Technology Letters, 2008, 20, 1042-1044.	1.3	1
86	Fewest vias design for microstrip guard trace by using overlying dielectric. , 2008, , .		16
87	Placement of shorting vias for power integrity in multi-layered structures. , 2008, , .		0
88	Reflection Enhanced Compensation of Lossy Traces for Best Eye-Diagram Improvement Using High-Impedance Mismatch. IEEE Transactions on Advanced Packaging, 2008, 31, 619-626.	1.7	23
89	The effects on SI and EMI for differential coupled microstrip lines over LPC-EBG power/ground planes. , 2008, , .		4
90	Delaunayâ€™Voronoi Modeling of Power-Ground Planes With Source Port Correction. IEEE Transactions on Advanced Packaging, 2008, 31, 303-310.	1.7	43

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91	Signal integrity analysis of DDR3 high-speed memory module. , 2008, , .		8
92	Designs of signal-ground bump-patterns for minimizing the simultaneous switching noise in a ball grid array. , 2008, , .		1
93	Multilayer 180°; hybrid in LTCC. , 2008, , .		2
94	Design of Reflectionless Vias Using Neural Network-Based Approach. IEEE Transactions on Advanced Packaging, 2008, 31, 211-218.	1.7	15
95	Highly-directed terahertz photonic transmitter by using the design of planar antenna arrays. , 2008, , .		0
96	Design of Compact Branch-Line Coupler with Coupled Resonators. , 2007, , .		15
97	A Vertically Stacked Quasi-Elliptic Waveguide Filter with Crossly Coupling Vias. , 2007, , .		7
98	The microwave activity and progress in National Taiwan University. , 2007, , .		0
99	Fast Algorithm for Determining Eye-Diagram Characteristics of Lossy Transmission Lines. , 2007, , .		2
100	Design of A Vertically Stacked Substrate Integrated Folded-Waveguide Resonator Filter in LTCC. , 2007, , .		7
101	An Integrated Signal and Power Integrity Analysis for Signal Traces Through the Parallel Planes Using Hybrid Finite-Element and Finite-Difference Time-Domain Techniques. IEEE Transactions on Advanced Packaging, 2007, 30, 558-565.	1.7	15
102	Design of 30GHz Transition between Microstrip Line and Substrate Integrated Waveguide. , 2007, , .		9
103	Reflectionless Design for Differential-Via Transitions Using Neural Network-Based Approach. , 2007, , .		5
104	Microwave Activities in Taiwan. IEEE MTT-S International Microwave Symposium Digest IEEE MTT-S International Microwave Symposium, 2007, , .	0.0	0
105	Improvements of Time-Domain Transmission Waveform in Serpentine Delay Line with Guard Traces. , 2007, , .		6
106	A Dual Pass Band Filter with Embedded CPW Resonator. , 2007, , .		0
107	Design of Vertically Stacked Waveguide Filters in LTCC. IEEE Transactions on Microwave Theory and Techniques, 2007, 55, 1771-1779.	2.9	65
108	Novel compact net-type resonators and their applications to microstrip bandpass filters. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 755-762.	2.9	47

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109	Design of Wideband Impedance Matching for Through-Hole Via Transition Using Ellipse-Shaped Anti-Pad. , 2006, , .		20
110	An Efficient and Flexible Modeling for Power/Ground Planes. , 2006, , .		1
111	A Systematic Design to Suppress Wideband Ground Bounce Noise in High-Speed Circuits by Electromagnetic-Bandgap-Enhanced Split Powers. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 4209-4217.	2.9	44
112	Comparisons between serpentine and flat spiral delay lines on transient reflection/transmission waveforms and eye diagrams. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 1379-1387.	2.9	42
113	Terahertz Microchip for Illicit Drug Detection. IEEE Photonics Technology Letters, 2006, 18, 2254-2256.	1.3	44
114	Frequency tunability of terahertz photonic transmitters. Applied Physics Letters, 2006, 88, 093501.	1.5	8
115	Design of a vertically stacked waveguide filter with novel cross coupling structures in LTCC. , 2006, , .		5
116	Microstrip diplexers design with common resonator sections for compact size, but high isolation. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 1945-1952.	2.9	230
117	Steady-state response by finite-difference time-domain method and lanczos algorithm. IEEE Transactions on Microwave Theory and Techniques, 2006, 54, 3038-3044.	2.9	2
118	Miniaturized Microstrip Quasi-Elliptical Bandpass Filters Using Slotted Resonators. , 2006, , .		6
119	Hybrid TIE/FDTD Method for Open Boundary Coupling Between Isolation Islands. IEEE Transactions on Advanced Packaging, 2006, 29, 623-630.	1.7	1
120	A miniaturized microstrip common resonator triplexer without extra matching network. , 2006, , .		17
121	Terahertz biochip for illicit drug detection. , 2006, , .		0
122	Noise Reduction Using Compensation Capacitance for Bend Discontinuities of Differential Transmission Lines. IEEE Transactions on Advanced Packaging, 2006, 29, 560-569.	1.7	80
123	A miniaturized multilayer quasi-elliptic bandpass filter with aperture-coupled microstrip resonators. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 2688-2692.	2.9	26
124	Design of microstrip bandpass filters with multiorder spurious-mode suppression. IEEE Transactions on Microwave Theory and Techniques, 2005, 53, 3788-3793.	2.9	182
125	Ka-band 32-GHz planar integrated switched-beam smart antenna. , 2005, , .		2
126	Bandwidth enhancement on waveguide transition to conductor backed CPW with high dielectric constant substrate. IEEE Microwave and Wireless Components Letters, 2005, 15, 128-130.	2.0	17



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127	Broadband-response and frequency-tunable terahertz photonic transmitters with high efficiency. , 2005, , .		1
128	A miniaturized net-type microstrip bandpass filter using $\lambda/8$ resonators. IEEE Microwave and Wireless Components Letters, 2005, 15, 481-483.	2.0	17
129	A dual band elliptical DRA. , 2004, , .		2
130	Synthesis of nonuniformly spaced linear array for GSM/DCS/WCDMA base station application using genetic algorithm. , 2004, , .		5
131	A Circular Polarizer Designed With a Dielectric Septum Loading. IEEE Transactions on Microwave Theory and Techniques, 2004, 52, 1719-1723.	2.9	63
132	A 650 GHz photonic transmitter design using CPW-fed slot antenna. , 2004, , .		0
133	Device Saturation Behavior of Submillimeter-Wave Membrane Photonic Transmitters. IEEE Photonics Technology Letters, 2004, 16, 873-875.	1.3	15
134	Millimeter-Wave MMIC Passive HEMT Switches Using Traveling-Wave Concept. IEEE Transactions on Microwave Theory and Techniques, 2004, 52, 1798-1808.	2.9	82
135	Reduction in reflections and ground bounce for signal line through a split power plane by using differential coupled microstrip lines. , 2003, , .		9
136	An improved formalism for FDTD analysis of thin-slot problems by conformal mapping technique. IEEE Transactions on Antennas and Propagation, 2003, 51, 2530-2533.	3.1	24
137	Modeling and design for electrical performance of wideband flip-chip transition. IEEE Transactions on Advanced Packaging, 2003, 26, 385-391.	1.7	42
138	A Broadband Microstrip-to-Waveguide Transition with Tapered CPS Probe. , 2002, , .		13
139	Highly Selective Microstrip Bandpass Filters in Ka-Band. , 2002, , .		17
140	Composite effects of reflections and ground bounce for signal line through a split power plane. IEEE Transactions on Advanced Packaging, 2002, 25, 297-301.	1.7	18
141	CPW to waveguide transition with tapered slotline probe. IEEE Microwave and Wireless Components Letters, 2001, 11, 314-316.	2.0	44
142	Partially prism-gridded FDTD analysis for layered structures of transversely curved boundary. IEEE Transactions on Microwave Theory and Techniques, 2000, 48, 339-346.	2.9	5
143	Computations for radiation and surface-wave losses in coplanar waveguide bandpass filters. IEEE Transactions on Microwave Theory and Techniques, 1999, 47, 385-389.	2.9	8
144	The use of symmetry to simplify the mixed-potential integral-equation method with application to N-way radial power dividers/combiners with isolation resistors. IEEE Transactions on Microwave Theory and Techniques, 1999, 47, 1609-1616.	2.9	7

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145	A wide-band multiport planar power-divider design using matched sectorial components in radial arrangement. IEEE Transactions on Microwave Theory and Techniques, 1998, 46, 1072-1078.	2.9	27
146	Hybrid finite-difference time-domain modeling of curved surfaces using tetrahedral edge elements. IEEE Transactions on Antennas and Propagation, 1997, 45, 1302-1309.	3.1	66
147	Analysis of coplanar-waveguide discontinuities with finite-metallization thickness and nonrectangular edge profile. IEEE Transactions on Microwave Theory and Techniques, 1997, 45, 2131-2138.	2.9	9
148	Capacitance computation for CPW discontinuities with finite metallization thickness by hybrid finite-element method. IEEE Transactions on Microwave Theory and Techniques, 1997, 45, 498-504.	2.9	13
149	Modeling of microwave active devices using the FDTD analysis based on the voltage-source approach. , 1996, 6, 199-201.		70
150	A wideband waveguide transition design with modified dielectric transformer using edge-based tetrahedral finite-element analysis. IEEE Transactions on Microwave Theory and Techniques, 1996, 44, 1024-1031.	2.9	6
151	Analysis of edge slots in rectangular waveguide with finite waveguide wall thickness. IEEE Transactions on Antennas and Propagation, 1996, 44, 1120-1126.	3.1	16
152	Flat spiral delay line design with minimum crosstalk penalty. IEEE Transactions on Advanced Packaging, 1996, 19, 397-402.	0.7	37
153	A hybrid spatial domain analysis of the Wilkinson power divider. , 1996, , .		2
154	Full-wave characterization of a through hole via in multi-layered packaging. IEEE Transactions on Microwave Theory and Techniques, 1995, 43, 1073-1081.	2.9	49
155	Laddering wave in serpentine delay line. IEEE Transactions on Advanced Packaging, 1995, 18, 644-650.	0.7	56
156	A scalar variational conformal mapping technique for weakly guiding dielectric waveguides. IEEE Journal of Quantum Electronics, 1986, 22, 603-609.	1.0	6
157	Variational reaction formulation of scattering problem for anisotropic dielectric cylinders. IEEE Transactions on Antennas and Propagation, 1986, 34, 640-645.	0.8	37
158	Propagation of Waves through Magnetoplasrna Slab Within a Parallel-Plate Guide. IEEE Transactions on Microwave Theory and Techniques, 1986, 34, 32-37.	2.9	3
159	Birefringence Analysis of Anisotropic Optical Fibers Using Variational Reaction Theory. IEEE Transactions on Microwave Theory and Techniques, 1986, 34, 741-745.	2.9	2
160	On the Variational Reaction Theory for Dielectric Waveguides. IEEE Transactions on Microwave Theory and Techniques, 1985, 33, 477-483.	2.9	17
161	Scattering analysis of optical fibers in spectral domain. , 0, , .		0
162	Full-Wave Iterative Variational Formulation for Multiple Coupled Microstrip Lines. , 0, , .		0

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163	Equivalent circuit of a through via in multi-layer environment. , 0, , .		3
164	Full wave characterization of a through hole via discontinuity in multi-layered packaging. , 0, , .		3
165	Laddering wave in serpentine delay line. , 0, , .		0
166	Quick inspection of power-plane short fault on multichip module. , 0, , .		0
167	A new flat spiral routing to minimize crosstalk penalty in delay line. , 0, , .		1
168	Inspection of short fault in power-plane with irregular and perforated shapes [MCMs]. , 0, , .		0
169	Electrical and mechanical studies of MCM-D interconnect structure. , 0, , .		1
170	Hybridizing FD-TD analysis with unconditionally stable FEM for objects of curved boundary. , 0, , .		10
171	Comparative performance of three different CPW bandpass filters. , 0, , .		6
172	Equivalent inductances of coplanar-stripline step discontinuities. , 0, , .		0
173	A wide band multiport planar power divider design by radially combining matched sectorial components. , 0, , .		2
174	Hybrid FEM analysis of thick CPW discontinuities with nonrectangular cross section. , 0, , .		0
175	A simplified MPIE analysis for planar circuits with N-fold rotational symmetry and lumped elements. , 0, , .		0
176	Partially prism-gridded FDTD analysis for layered structures of transversely curved boundary. , 0, , .		1
177	Treating late-time instability of partially tetrahedral-gridded finite difference time domain method. , 0, , .		0
178	A resonant flip-chip design with controllable transition band. , 0, , .		2
179	Composite effects of reflections and ground bounce for signal vias in multi-layer environment. , 0, , .		3
180	Locally matching design for flip-chip transition. , 0, , .		1

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181	Hermetic housing design for TR module in LMDS system. , 0, , .		0
182	Analysis of microstrip antennas with finite-sized substrate. , 0, , .		1
183	Composite effects of reflections and ground bounce for signal line through a split power plane. , 0, , .		0
184	A locally matching technique for broadband flip-chip transition design. , 0, , .		2
185	Analysis of microstrip antennas with inhomogeneous and finite-sized substrate. , 0, , .		0
186	Two-dimensional finite-difference time-domain method combined with open boundary for signal integrity issues between isolation islands. , 0, , .		3
187	Steady-state response by time-reversal FD-TD method with Lanczos algorithm. , 0, , .		1
188	Conversion efficiency and device behavior of edge-coupled membrane photonic transmitters. , 0, , .		0
189	Modeling antenna array elements and bandwidth enhanced by genetic algorithm. , 0, , .		0
190	Circuit modeling and noise reduction for bent differential transmission lines. , 0, , .		1
191	Comparison between flat spiral and serpentine differential delay lines on TDR and TDT. , 0, , .		1
192	A Wide-stopband Low-pass Filter Design Based on Multi-period Taper-etched EBG Structure. , 0, , .		2
193	Compact Microstrip Cross-Coupled Bandpass Filters Using Miniaturized Stepped Impedance Resonators. , 0, , .		10
194	Model Extractions of Coupled Bonding-wire Structures in Electronic Packaging. , 0, , .		5
195	Combined FDTD/FETD algorithm for ground bounce characterization of differential traces through the planes. , 0, , .		0
196	EBG-enhanced split power planes for wideband noise suppression. , 0, , .		2
197	Design of 60-GHz Vertically Stacked Waveguide Filters in LTCC. , 0, , .		0
198	A 60GHz LTCC Transition between Microstrip Line and Substrate Integrated Waveguide. , 0, , .		9

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199	Design and Modeling of Microstrip Line to Substrate Integrated Waveguide Transitions. , 0, , .		8